

Docket No. 202009US-2 DIV

IN RE APPLICATION OF: Shigenobu MAEDA

SERIAL NO: 09/761,738

FILED: January 18, 2001

FOR: MANUFACTURING METHOD OF SEMICONDUCTOR WAFER, SEMICONDUCTOR MANUFACTURING...



ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

SIR:

Transmitted herewith is an amendment in the above-identified application.

- ☒ No additional fee is required
- ☐ Small entity status of this application under 37 C.F.R. §1.9 and §1.27 is claimed.
- ☒ Additional documents filed herewith: Marked-Up Copy

The Fee has been calculated as shown below:

CLAIMS	CLAIMS REMAINING		HIGHEST NUMBER PREVIOUSLY PAID	NO. EXTRA CLAIMS	RATE	CALCULATIONS
TOTAL	4	MINUS	20	0	× \$18 =	\$0.00
INDEPENDENT	1	MINUS	3	0	× \$84 =	\$0.00
		<input type="checkbox"/> MULTIPLE DEPENDENT CLAIMS			+ \$280 =	\$0.00
		TOTAL OF ABOVE CALCULATIONS				\$0.00
		<input type="checkbox"/> Reduction by 50% for filing by Small Entity				\$0.00
		<input type="checkbox"/> Recordation of Assignment			+ \$40 =	\$0.00
		TOTAL				\$0.00

- ☐ A check in the amount of _____ is attached.
- ☒ Please charge any additional Fees for the papers being filed herewith and for which no check is enclosed herewith, or credit any overpayment to deposit Account No. 15-0030. A duplicate copy of this sheet is enclosed.
- ☒ If these papers are not considered timely filed by the Patent and Trademark Office, then a petition is hereby made under 37 C.F.R. §1.136, and any additional fees required under 37 C.F.R. §1.136 for any necessary extension of time may be charged to Deposit Account No. 15-0030. A duplicate copy of this sheet is enclosed.

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202009US-2DIV

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF

SHIGENOBU MAEDA

SERIAL NO: 09/761,738

FILED: JANUARY 18, 2001



EXAMINER: PYONIN, A.

: GROUP ART UNIT: 2824

FOR: MANUFACTURING METHOD OF:
SEMICONDUCTOR WAFER,
SEMICONDUCTOR MANUFACTURING
APPARATUS, AND SEMICONDUCTOR
DEVICE

5#/Amat B
1/31/02
Rbm

AMENDMENT

ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

SIR:

Responsive to the Official Action mailed October 24, 2001, please amend the above-identified patent application as follows:

IN THE SPECIFICATION

Please delete the title of the invention in its entirety and substitute therefor:

MANUFACTURING METHOD OF CIRCUIT ELEMENTS ON
A SEMICONDUCTOR WAFER USING A PLURALITY OF MASKS

IN THE CLAIMS

Please amend Claims 21 and 22 as follows:

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